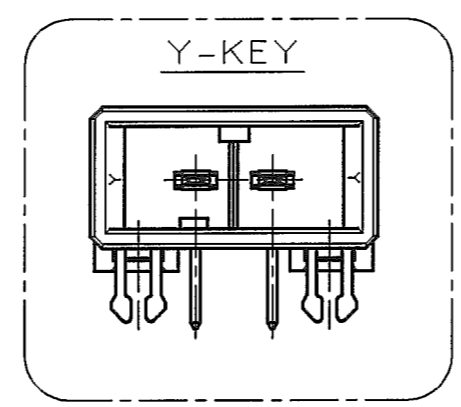
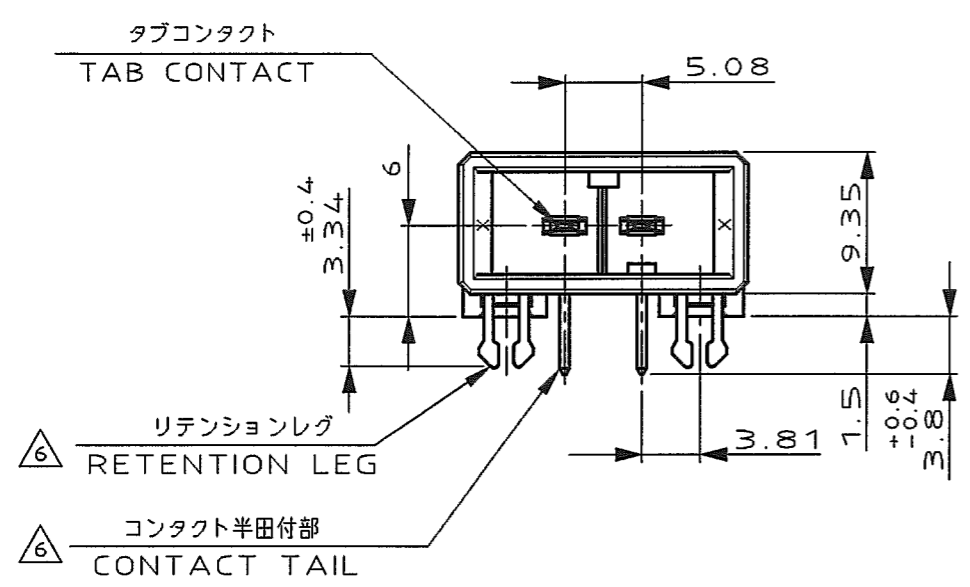
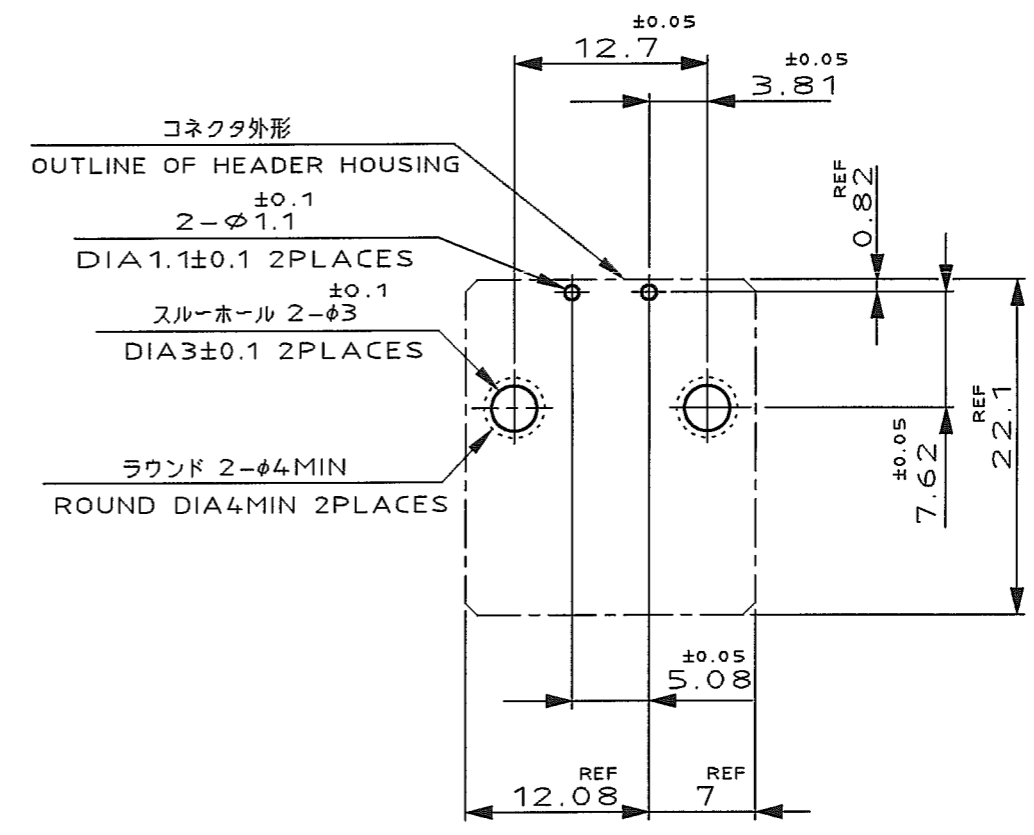
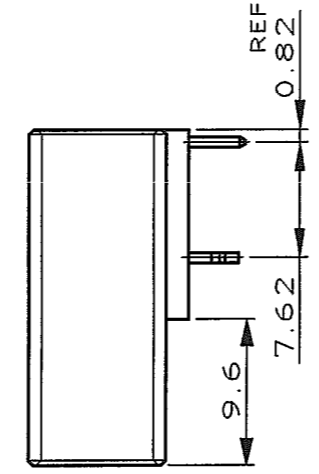
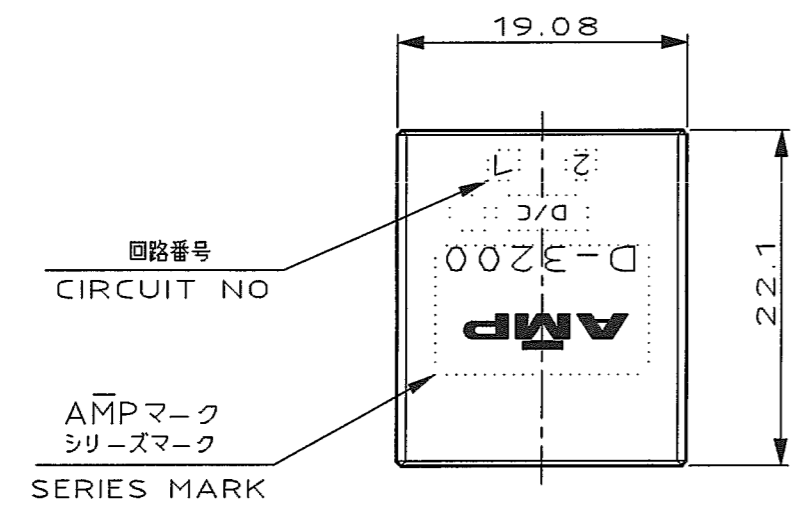


NUMBER 179276  
 METRIC  
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT  
 PRINT DIST



推奨基板取付け穴寸法  
 PC 基板厚: 1.6±0.1  
 (非累積公差)  
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
 PC BOARD THICKNESS: 1.6±0.1  
 (NOT ACCUMULATE TOLERANCE)  
 (CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER  
 CONTACT: COPPER ALLOY  
 RETENTION LEG: COPPER ALLOY
2. FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
3. FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
5. FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
7. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂  
 コネクタ: 銅合金  
 リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地  
 接触部: 0.38μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地  
 接触部: 0.76μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地  
 接触部: 2.0 μm MINスズめっき
5. めっき: リテンションレグとコンタクト半田付部  
 ニッケル下地の上に半田めっき
6. めっき: リテンションレグとコンタクト半田付部  
 ニッケル下地の上にスズめっき

OBSOLETE	6	4	2-179276-5	Y
	6	3	2-179276-3	Y
	6	2	2-179276-2	Y
	6	4	1-179276-5	X
	6	3	1-179276-3	X
	6	2	1-179276-2	X
(FINISH)		製品番号 (PART NO.)	KEY	

B2	REVISED PER ECO-11-005030	RK	HMR	22MAR11
LTR	REVISION RECORD	DR	CHK	DATE

DR. 1 DEC 93 N. Matsubara	DE. 1 DEC 93 N. Matsubara
CHK. 13 DEC 93 S. MANABE	APP. 13 DEC 93 S. MANABE

NAME 2 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200			
一般公差 (GENERAL TOLERANCE)	SIZE	LOC	NUMBER
10MF : ±0.2 100MF : ±0.3 300MF : ±0.4 角 度 : ±3'	A3	J	C-179276
SCALE	REV.	SHEET	
2-1	B2	1 OF 1	

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[1-179276-3](#)